Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1851	257/666,670,672,674,690,692, 723,724,784,787,E23.031,E23. 033,E23.037,E23.043.ccls. and (chip die ic) adj2 (pad bonding adj area) and wire and (encapsulant resin epoxy mold$3 adj compound)	USPAT	OR	ON	2006/02/12 17:34
L2	800	257/666,670,672,674,690,692, 723,724,784,787,E23.031,E23. 033,E23.037,E23.043.ccls. and (chip die ic) adj2 (pad bonding adj area) and wire and (encapsulant resin epoxy mold$3 adj compound) same (expos$2 uncover$3)	USPAT	OR	ON	2006/02/12 17:51
L3	259	438/110-112,121,123.ccls. and (chip die ic) adj2 (pad bonding adj area) and wire and (encapsulant resin epoxy mold$3 adj compound) same (expos$2 uncover$3)	USPAT	OR	ON	2006/02/12 17:55
L4	59	361/723,772,773,813.ccls. and (chip die ic) adj2 (pad bonding adj area) and wire and (encapsulant resin epoxy mold$3 adj compound) same (expos$2 uncover$3)	USPAT	OR	ON	2006/02/12 17:57